

Appl. No.: 10/606,508  
Response Dated: 01/17/2006  
Reply to Office Action of: 10/17/2005

IFW



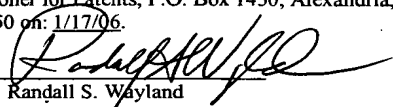
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : 10/606,508  
Applicant : James J. Bernas, et al.  
Filed : 6/26/03  
Title : Double-Skin Honeycomb Substrate and  
Extrusion Die Assembly for Making the Same  
TC/A.U. : 1775  
Examiner : Ling X. Xu  
Docket No. : SP03-073

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**CERTIFICATE OF MAILING (37 CFR 1.8a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on: 1/17/06.

  
Randall S. Wayland

**AMENDMENT**

Sir:

In response to the Office communication mailed on 10/17/2005, please amend the above-identified as follows:

**Amendments to the Specification - page 2 following;**

**Amendments to the Claims – page 3 following;**

**Remarks/Arguments – page 6 following.**